

72Mb Sync. Flow-Trough SRAM Specification

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S7B643635M
S7B641835M

2Mx36 & 4Mx18 Flow-Trough SRAM

Document Title

2Mx36 & 4Mx18 Bit Flow-Trough SRAM

Revision History

Rev. No.	History	Draft Date	Remark
1.0	Final Spec Release	Sep. 2014	Final

S7B643635M S7B641835M

2Mx36 & 4Mx18 Flow-Trough SRAM

2Mx36 & 4Mx18 Bit Flow-Trough SRAM

Features

- V_{DD} = 2.5V(2.3V ~ 2.7V) or 3.3V(3.1V ~ 3.5V) Power Supply
- V_{DDQ} = 2.3V~2.7V I/O Power Supply (V_{DD}=2.5V) or 2.3V~3.5V I/O Power Supply (V_{DD}=3.3V)
- Synchronous Operation
- Self-Timed Write Cycle
- On-Chip Address Counter and Control Registers
- Byte Writable Function
- Global Write Enable Controls a full bus-width write
- Power Down State via ZZ Signal
- LBO Pin allows a choice of either a interleaved burst or a linear burst
- Three Chip Enables for simple depth expansion with No Data Contention only for TQFP
- Asynchronous Output Enable Control
- ADSP, ADSC, ADV Burst Control Pins
- TTL-Level Three-State Output
- Operating in commercial and industrial temperature range
- 100-TQFP-1420A (Lead free package)
- 165FBGA(11x15 ball array) with body size of 13mmx15mm. (Lead free package)

General Description

The S7B643635M and S7B641835M are 75,497,472-bit Synchronous Static Random Access Memory designed for high performance.

It is organized as 2M(4M) words of 36(18) bits and integrates address and control registers, a 2-bit burst address counter and added some new functions for high performance applications; \overline{GW} , \overline{BW} , LBO, ZZ. Write cycles are internally self-timed and synchronous.

Full bus-width write is done by \overline{GW} , and each byte write is performed by the combination of \overline{WEx} and \overline{BW} when \overline{GW} is high. And with \overline{CS}_1 high, \overline{ADSP} is blocked to control signals.

Burst cycle can be initiated with either the address status processor(\overline{ADSP}) or address status cache controller(\overline{ADSC}) inputs. Subsequent burst addresses are generated internally in the system's burst sequence and are controlled by the burst address advance(\overline{ADV}) input.

\overline{LBO} pin is DC operated and determines burst sequence(linear or interleaved).

ZZ pin controls Power Down State and reduces Stand-by current regardless of CLK.

The S7B643635M and S7B641835M are fabricated using high performance CMOS technology and is available in a 100pin TQFP package and 165FBGA package. Multiple power and ground pins are utilized to minimize ground bounce.

Key Parameters

Parameter	Symbol	-65	-75	Unit
Cycle Time	tCYC	7.5	8.5	ns
Clock Access Time	tCD	6.5	7.5	ns
Output Enable Access Time	tOE	3.5	3.5	ns
Operating Current	I _{cc}	330	320	mA
Standby Current	I _{SB2}	200	200	mA

72Mb Flow-Through SRAM Ordering Information

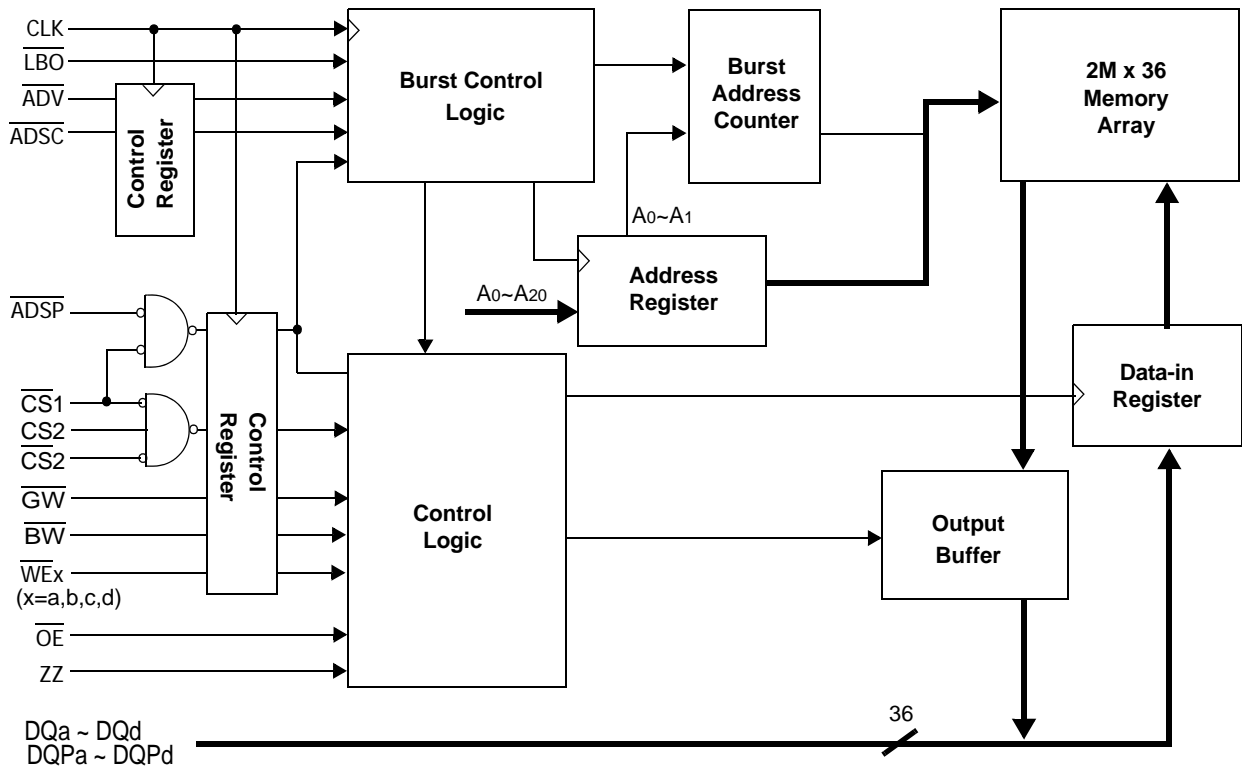
Org.	VDD (V)	Speed (ns)	Access Time (ns)	Part Number	RoHS Avail.
4Mx18	3.3/2.5	7.5	6.5	S7B641835M-P(E)C(I)65	0
	3.3/2.5	8.5	7.5	S7B641835M-P(E)C(I)75	0
2Mx36	3.3/2.5	7.5	6.5	S7B643635M-P(E)C(I)65	0
	3.3/2.5	8.5	7.5	S7B643635M-P(E)C(I)75	0

- Note 1. P(E) [Package type] : P - 100TQFP Pb Free, E - 165FBGA Pb Free
2. C(I) [Operating Temperature] : C-Commercial, I-Industrial

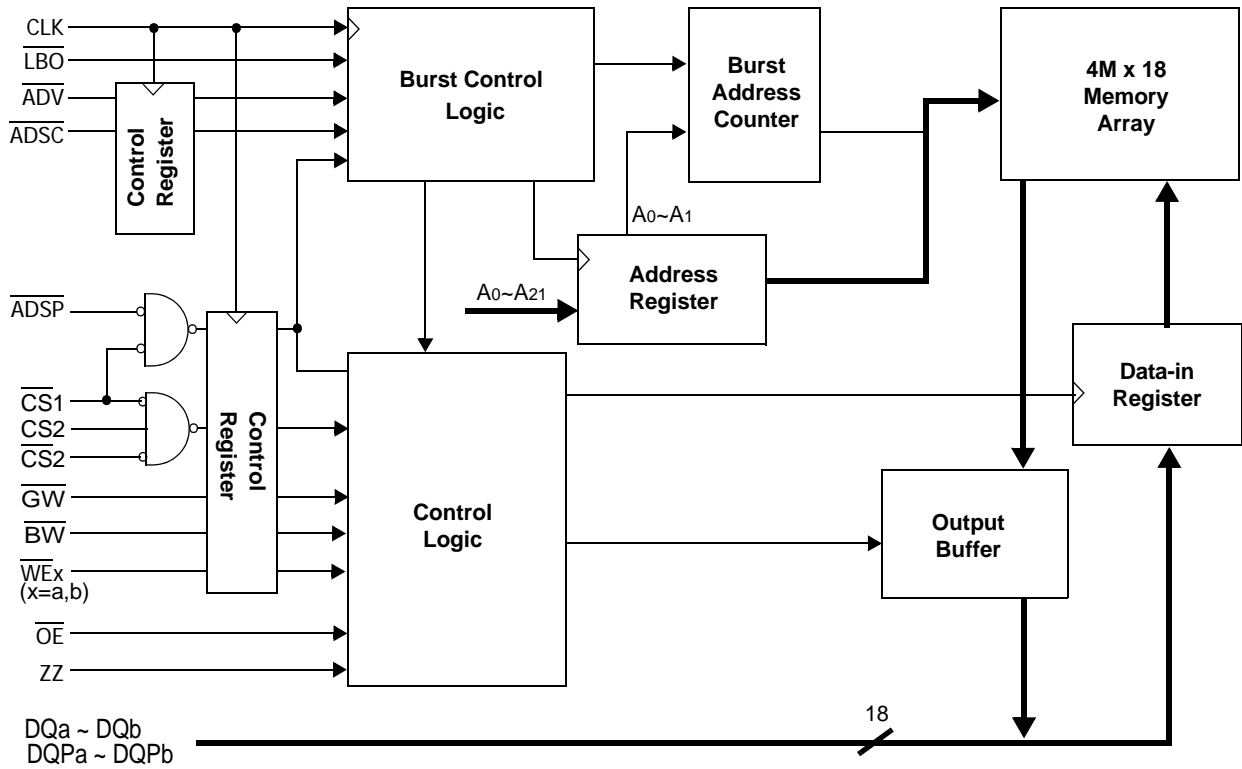
S7B643635M
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2Mx36 & 4Mx18 Flow-Trough SRAM

Logic Block Diagram - S7B643635M (2M x 36)



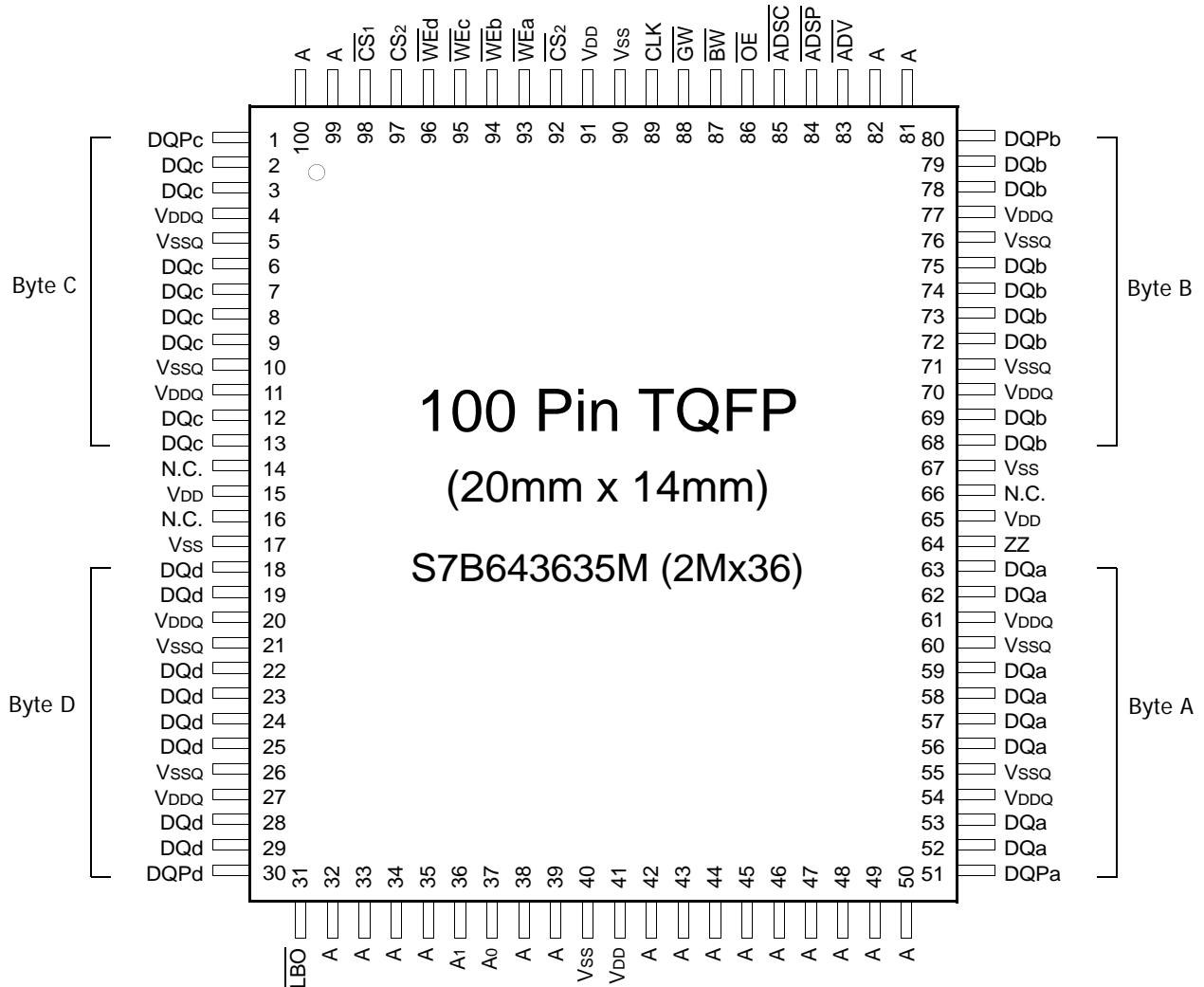
Logic Block Diagram - S7B641835M (4M x 18)



S7B643635M
S7B641835M

2Mx36 & 4Mx18 Flow-Trough SRAM

100 TQFP Package Pin Configurations(Top View)



Pin Name

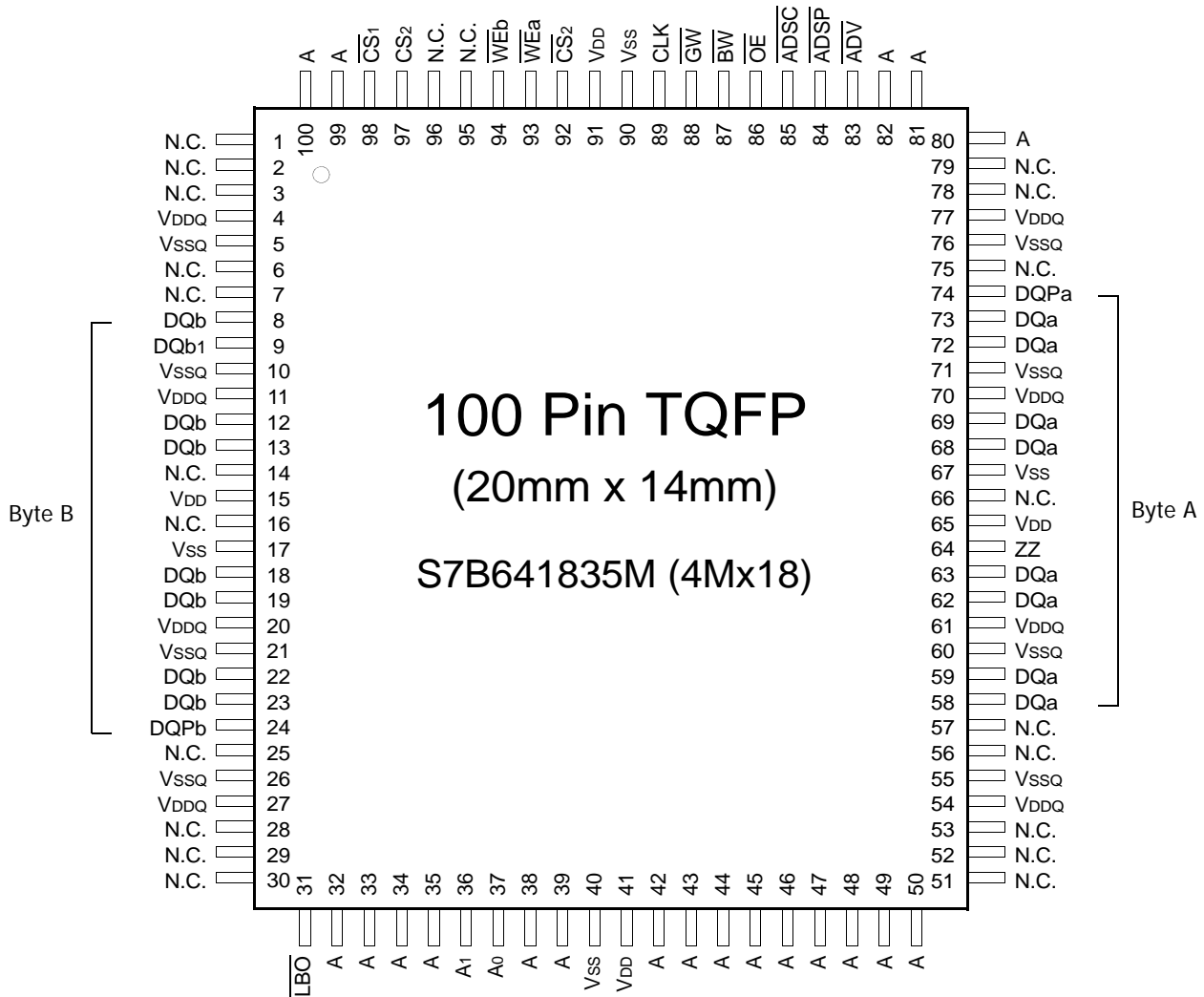
Symbol	Pin Name	TQFP Pin NO.	Symbol	Pin Name	TQFP Pin NO.
A	Address Inputs	32,33,34,35,38,39,42,43,44,45,46,47,48,49,50,81,82,99,100	VDD	Power Supply (2.5V~3.3V)	15,41,65,91
A0,A1	Burst Address Inputs	37,36	VSS	Ground	17,40,67,90
ADV	Burst Address Advance	83	N.C.	No Connect	14,16,66
ADSP	Address Status Processor	84	DQa	Data Inputs/Outputs	52,53,56,57,58,59,62,63,68,69,72,73,74,75,78,79
ADSC	Address Status Controller	85	DQb		2,3,6,7,8,9,12,13
CLK	Clock	89	DQc		18,19,22,23,24,25,28,29
CS1	Chip Select	98	DQd		51,80,1,30
CS2	Chip Select	97	DQPa~Pd		
CS2	Chip Select	92	VDDQ	Output Power Supply (2.5V~3.3V)	4,11,20,27,54,61,70,77
WEx(x=a,b,c,d)	Byte Write Inputs	93,94,95,96	VSSQ	Output Ground	5,10,21,26,55,60,71,76
OE	Output Enable	86			
GW	Global Write Enable	88			
BW	Byte Write Enable	87			
ZZ	Power Down Input	64			
LBO	Burst Mode Control	31			

Note : 1. A0 and A1 are the two least significant bits(LSB) of the address field and set the internal burst counter if burst is desired.

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2Mx36 & 4Mx18 Flow-Trough SRAM

100 TQFP Package Pin Configurations (Top View)



Pin Name

Symbol	Pin Name	TQFP Pin NO.	Symbol	Pin Name	TQFP Pin NO.
A	Address Inputs	32,33,34,35,38,39,42,43,44,45,46,47,48,49,50,80,81,82,99,100	VDD	Power Supply (2.5V~3.3V)	15,41,65,91
A0,A1	Burst Address Inputs	37,36	VSS	Ground	17,40,67,90
ADV	Burst Address Advance	83	N.C.	No Connect	1,2,3,6,7,14,16,25,28,29,30,51,52,53,56,57,66,75,78,79,95,96
ADSP	Address Status Processor	84			
ADSC	Address Status Controller	85			
CLK	Clock	89	DQa	Data Inputs/Outputs	58,59,62,63,68,69,72,73
CS1	Chip Select	98	DQb		8,9,12,13,18,19,22,23
CS2	Chip Select	97	DQPa, Pb		74,24
CS2	Chip Select	92			
WEx(x=a,b)	Byte Write Inputs	93,94	VDDQ	Output Power Supply (2.5V~3.3V)	4,11,20,27,54,61,70,77
OE	Output Enable	86	VSSQ	Output Ground	5,10,21,26,55,60,71,76
GW	Global Write Enable	88			
BW	Byte Write Enable	87			
ZZ	Power Down Input	64			
LBO	Burst Mode Control	31			

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S7B641835M

2Mx36 & 4Mx18 Flow-Trough SRAM

165FBGA PKG Pin Configurations - S7B643635M (2Mx36) - Top View

	1	2	3	4	5	6	7	8	9	10	11
A	NC	A	$\overline{CS1}$	\overline{WE}_c	\overline{WE}_b	$\overline{CS2}$	\overline{BW}	\overline{ADSC}	\overline{ADV}	A	NC
B	NC	A	CS2	\overline{WE}_d	\overline{WE}_a	CLK	\overline{GW}	\overline{OE}	\overline{ADSP}	A	NC
C	DQP _c	NC	VDDQ	VSS	VSS	VSS	VSS	VSS	VDDQ	NC	DQP _b
D	DQ _c	DQ _c	VDDQ	VDD	VSS	VSS	VSS	VDD	VDDQ	DQ _b	DQ _b
E	DQ _c	DQ _c	VDDQ	VDD	VSS	VSS	VSS	VDD	VDDQ	DQ _b	DQ _b
F	DQ _c	DQ _c	VDDQ	VDD	VSS	VSS	VSS	VDD	VDDQ	DQ _b	DQ _b
G	DQ _c	DQ _c	VDDQ	VDD	VSS	VSS	VSS	VDD	VDDQ	DQ _b	DQ _b
H	NC	NC	NC	VDD	VSS	VSS	VSS	VDD	NC	NC	ZZ
J	DQ _d	DQ _d	VDDQ	VDD	VSS	VSS	VSS	VDD	VDDQ	DQ _a	DQ _a
K	DQ _d	DQ _d	VDDQ	VDD	VSS	VSS	VSS	VDD	VDDQ	DQ _a	DQ _a
L	DQ _d	DQ _d	VDDQ	VDD	VSS	VSS	VSS	VDD	VDDQ	DQ _a	DQ _a
M	DQ _d	DQ _d	VDDQ	VDD	VSS	VSS	VSS	VDD	VDDQ	DQ _a	DQ _a
N	DQP _d	NC	VDDQ	VSS	NC	A	NC	VSS	VDDQ	NC	DQP _a
P	NC	A	A	A	TDI	A1*	TDO	A	A	A	A
R	\overline{LBO}	A	A	A	TMS	A0*	TCK	A	A	A	A

Notes: * A0 and A1 are two least significant bits(LSB) of the address field and set the internal burst counter if burst is desired.

Pin Name

Symbol	Pin Name	Symbol	Pin Name
A	Address Inputs	VDD	Power Supply (2.5V~3.3V)
A0,A1	Burst Address Inputs	VSS	Ground
\overline{ADV}	Burst Address Advance	N.C.	No Connect
\overline{ADSP}	Address Status Processor		
\overline{ADSC}	Address Status Controller		
CLK	Clock		
$\overline{CS1}$	Chip Select	DQa	Data Inputs/Outputs
$\overline{CS2}$	Chip Select	DQb	
$\overline{CS2}$	Chip Select	DQc	
$\overline{WE}_{x(x=a,b,c,d)}$	Byte Write Inputs	DQd	
\overline{OE}	Output Enable	DQPa~Pd	
\overline{GW}	Global Write Enable		
\overline{BW}	Byte Write Enable	VDDQ	Output Power Supply (2.5V~3.3V)
\overline{ZZ}	Power Down Input	VSSQ	Output Ground
\overline{LBO}	Burst Mode Control		

Note : 1. A0 and A1 are the two least significant bits(LSB) of the address field and set the internal burst counter if burst is desired.

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S7B641835M

2Mx36 & 4Mx18 Flow-Trough SRAM

165FBGA PKG Pin Configurations - S7B641835M (4Mx18) - Top View

	1	2	3	4	5	6	7	8	9	10	11
A	NC	A	$\overline{\text{CS1}}$	$\overline{\text{WE}}_b$	NC	$\overline{\text{CS2}}$	$\overline{\text{BW}}$	$\overline{\text{ADSC}}$	$\overline{\text{ADV}}$	A	A
B	NC	A	CS2	NC	$\overline{\text{WE}}_a$	CLK	$\overline{\text{GW}}$	$\overline{\text{OE}}$	$\overline{\text{ADSP}}$	A	NC
C	NC	NC	VDDQ	VSS	VSS	VSS	VSS	VSS	VDDQ	NC	DQP _a
D	NC	DQ _b	VDDQ	VDD	VSS	VSS	VSS	VDD	VDDQ	NC	DQ _a
E	NC	DQ _b	VDDQ	VDD	VSS	VSS	VSS	VDD	VDDQ	NC	DQ _a
F	NC	DQ _b	VDDQ	VDD	VSS	VSS	VSS	VDD	VDDQ	NC	DQ _a
G	NC	DQ _b	VDDQ	VDD	VSS	VSS	VSS	VDD	VDDQ	NC	DQ _a
H	NC	NC	NC	VDD	VSS	VSS	VSS	VDD	NC	NC	ZZ
J	DQ _b	NC	VDDQ	VDD	VSS	VSS	VSS	VDD	VDDQ	DQ _a	NC
K	DQ _b	NC	VDDQ	VDD	VSS	VSS	VSS	VDD	VDDQ	DQ _a	NC
L	DQ _b	NC	VDDQ	VDD	VSS	VSS	VSS	VDD	VDDQ	DQ _a	NC
M	DQ _b	NC	VDDQ	VDD	VSS	VSS	VSS	VDD	VDDQ	DQ _a	NC
N	DQP _b	NC	VDDQ	VSS	NC	A	NC	VSS	VDDQ	NC	NC
P	NC	A	A	A	TDI	A1*	TDO	A	A	A	A
R	$\overline{\text{LBO}}$	A	A	A	TMS	A0*	TCK	A	A	A	A

Notes: * A0 and A1 are two least significant bits(LSB) of the address field and set the internal burst counter if burst is desired.

Pin Name

Symbol	Pin Name	Symbol	Pin Name
A	Address Inputs	VDD	Power Supply (2.5V~3.3V)
A0,A1	Burst Address Inputs	VSS	Ground
$\overline{\text{ADV}}$	Burst Address Advance	N.C.	No Connect
$\overline{\text{ADSP}}$	Address Status Processor		
$\overline{\text{ADSC}}$	Address Status Controller		
CLK	Clock		
$\overline{\text{CS1}}$	Chip Select	DQ _a	Data Inputs/Outputs
$\overline{\text{CS2}}$	Chip Select	DQ _b	
$\overline{\text{CS2}}$	Chip Select	DQP _a ~P _b	
$\overline{\text{WEx}}(x=a,b)$	Byte Write Inputs		
$\overline{\text{OE}}$	Output Enable	VDDQ	Output Power Supply (2.5V~3.3V)
$\overline{\text{GW}}$	Global Write Enable	VSSQ	Output Ground
$\overline{\text{BW}}$	Byte Write Enable		
$\overline{\text{ZZ}}$	Power Down Input		
$\overline{\text{LBO}}$	Burst Mode Control		

Note : 1. A0 and A1 are the two least significant bits(LSB) of the address field and set the internal burst counter if burst is desired.

Function Description

The S7B643635M and S7B641835M are synchronous SRAM designed to support the burst address accessing sequence of the Power PC based microprocessor. All inputs (with the exception of \overline{OE} , \overline{LBO} and \overline{ZZ}) are sampled on rising clock edges. The start and duration of the burst access is controlled by \overline{ADSC} , \overline{ADSP} and \overline{ADV} and chip select pins. The accesses are enabled with the chip select signals and output enabled signals. Wait states are inserted into the access with \overline{ADV} .

When \overline{ZZ} is pulled high, the SRAM will enter a Power Down State. At this time, internal state of the SRAM is preserved. When \overline{ZZ} returns to low, the SRAM normally operates after 2cycles of wake up time. \overline{ZZ} pin is pulled down internally.

Read cycles are initiated with \overline{ADSP} (or \overline{ADSC}) using the new external address clocked into the on-chip address register when both \overline{GW} and \overline{BW} are high or when \overline{BW} is low and \overline{WEa} , \overline{WEb} , \overline{WEc} , and \overline{WEd} are high. When \overline{ADSP} is sampled low, the chip selects are sampled active, and the output buffer is enabled with \overline{OE} . the data of cell array accessed by the current address are projected to the output pins.

Write cycles are also initiated with \overline{ADSP} (or \overline{ADSC}) and are differentiated into two kinds of operations; All byte write operation and individual byte write operation.

All byte write occurs by enabling \overline{GW} (independent of \overline{BW} and \overline{WEx}), and individual byte write is performed only when \overline{GW} is high and \overline{BW} is low. In S7B643635M, a 2Mx36 organization, \overline{WEa} controls \overline{DQa} and \overline{DQPa} , \overline{WEb} controls \overline{DQb} and \overline{DQPb} , \overline{WEc} controls \overline{DQc} and \overline{DQPc} and \overline{WEd} controls \overline{DQd} and \overline{DQPd} .

$\overline{CS1}$ is used to enable the device and conditions internal use of \overline{ADSP} and is sampled only when a new external address is loaded.

\overline{ADV} is ignored at the clock edge when \overline{ADSP} is asserted, but can be sampled on the subsequent clock edges. The address increases internally for the next access of the burst when \overline{ADV} is sampled low.

Addresses are generated for the burst access as shown below, The starting point of the burst sequence is provided by the external address. The burst address counter wraps around to its initial state upon completion. The burst sequence is determined by the state of the \overline{LBO} pin. When this pin is Low, linear burst sequence is selected. And this pin is High, Interleaved burst sequence is selected.

Burst Sequence Table

(Interleaved Burst, \overline{LBO} =High)

\overline{LBO} PIN	HIGH	Case 1		Case 2		Case 3		Case 4	
		A1	A0	A1	A0	A1	A0	A1	A0
	First Address	0	0	0	1	1	0	1	1
	↓	0	1	0	0	1	1	1	0
	↓	1	0	1	1	0	0	0	1
	Fourth Address	1	1	1	0	0	1	0	0

(Linear Burst, \overline{LBO} =Low)

\overline{LBO} PIN	LOW	Case 1		Case 2		Case 3		Case 4	
		A1	A0	A1	A0	A1	A0	A1	A0
	First Address	0	0	0	1	1	0	1	1
	↓	0	1	1	0	1	1	0	0
	↓	1	0	1	1	0	0	0	1
	Fourth Address	1	1	0	0	0	1	1	0

Note : 1. \overline{LBO} pin must be tied to High or Low, and Floating State must not be allowed.

Asynchronous Truth Table

Operation	\overline{ZZ}	\overline{OE}	I/O STATUS
Sleep Mode	H	X	High-Z
Read	L	L	DQ
	L	H	High-Z
Write	L	X	Din, High-Z
Deselected	L	X	High-Z

Notes

1. X means "Don't Care".
2. \overline{ZZ} pin is pulled down internally
3. For write cycles that following read cycles, the output buffers must be disabled with \overline{OE} , otherwise data bus contention will occur.
4. Sleep Mode means power down state of which stand-by current does not depend on cycle time.
5. Deselected means power down state of which stand-by current depends on cycle time.

Truth Tables

Synchronous Truth Table

\overline{CS}_1	CS_2	\overline{CS}_2	\overline{ADSP}	\overline{ADSC}	\overline{ADV}	\overline{Write}	CLK	Address Accessed	Operation
H	X	X	X	L	X	X	↑	N/A	Not Selected
L	L	X	L	X	X	X	↑	N/A	Not Selected
L	X	H	L	X	X	X	↑	N/A	Not Selected
L	L	X	X	L	X	X	↑	N/A	Not Selected
L	X	H	X	L	X	X	↑	N/A	Not Selected
L	H	L	L	X	X	X	↑	External Address	Begin Burst Read Cycle
L	H	L	H	L	X	L	↑	External Address	Begin Burst Write Cycle
L	H	L	H	L	X	H	↑	External Address	Begin Burst Read Cycle
X	X	X	H	H	L	H	↑	Next Address	Continue Burst Read Cycle
H	X	X	X	H	L	H	↑	Next Address	Continue Burst Read Cycle
X	X	X	H	H	L	L	↑	Next Address	Continue Burst Write Cycle
H	X	X	X	H	L	L	↑	Next Address	Continue Burst Write Cycle
X	X	X	H	H	H	H	↑	Current Address	Suspend Burst Read Cycle
H	X	X	X	H	H	H	↑	Current Address	Suspend Burst Read Cycle
X	X	X	H	H	H	L	↑	Current Address	Suspend Burst Write Cycle
H	X	X	X	H	H	L	↑	Current Address	Suspend Burst Write Cycle

Notes : 1. X means "Don't Care".

2. The rising edge of clock is symbolized by (↑).

3. $\overline{Write} = L$ means Write operation in Write Truth Table.

$\overline{Write} = H$ means Read operation in Write Truth Table.

4. Operation finally depends on status of asynchronous input pins(ZZ and OE).

Write Truth Table(x36)

\overline{GW}	\overline{BW}	\overline{WEa}	\overline{WEb}	\overline{WEc}	\overline{WEd}	Operation
H	H	X	X	X	X	Read
H	L	H	H	H	H	Read
H	L	L	H	H	H	Write Byte A
H	L	H	L	H	H	Write Byte B
H	L	H	H	L	L	Write Byte C And D
H	L	L	L	L	L	Write All Bytes
L	X	X	X	X	X	Write All Bytes

Notes : 1. X means "Don't Care".

2. All inputs in this table must meet setup and hold time around the rising edge of CLK(↑).

Write Truth Table(x18)

\overline{GW}	\overline{BW}	\overline{WEa}	\overline{WEb}	Operation
H	H	X	X	Read
H	L	H	H	Read
H	L	L	H	Write Byte A
H	L	H	L	Write Byte B
H	L	L	L	Write All Bytes
L	X	X	X	Write All Bytes

Notes : 1. X means "Don't Care".

2. All inputs in this table must meet setup and hold time around the rising edge of CLK(↑).

Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit	
Voltage on VDD Supply Relative to VSS	VDD	-0.3 to 4.6	V	
Voltage on VDDQ Supply Relative to VSS	VDDQ	VDD	V	
Voltage on Input Pin Relative to VSS	VIN	-0.3 to VDD+0.3	V	
Voltage on I/O Pin Relative to VSS	VIO	-0.3 to VDDQ+0.3	V	
Power Dissipation	PD	1.6	W	
Storage Temperature	TSTG	-65 to 150	°C	
Operating Temperature	Commercial	TOPR	0 to 70	°C
	Industrial	TOPR	-40 to 85	°C
Storage Temperature Range Under Bias	TBIAS	-10 to 85	°C	

Notes : Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operating sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Operating Conditions (0°C ≤ TA ≤ 70°C)

Parameter	Symbol	Min	Typ.	Max	Unit
Supply Voltage	VDD1	2.3	2.5	2.7	V
	VDDQ1	2.3	2.5	2.7	V
	VDD2	3.1	3.3	3.5	V
	VDDQ2	2.3	3.3	3.5	V
Ground	VSS	0	0	0	V

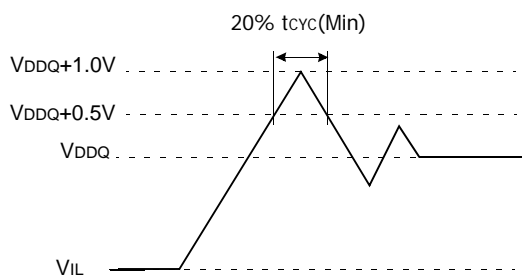
Notes: 1. The above parameters are also guaranteed at industrial temperature range.
 2. It should be VDDQ ≤ VDD

Capacitance (TA=25°C, f=1MHz)

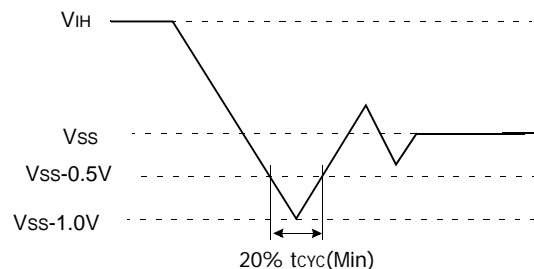
Parameter	Symbol	Test Condition	Min	Max	Unit
Input Capacitance	CIN	VIN=0V	-	5	pF
Output Capacitance	COUT	VOUT=0V	-	7	pF

Note : Sampled not 100% tested.

Overshoot Timing



Undershoot Timing



DC Electrical Characteristics

Parameter	Symbol	Test Conditions	Min	Max	Unit	Notes	
Input Leakage Current(except ZZ)	IIL	VDD=Max ; VIN=VSS to VDD	-2	+2	uA		
Output Leakage Current	IOL	Output Disabled, Vout=VSS to VDDQ	-2	+2	uA		
Operating Current	ICC	Device Selected, IOUT=0mA, ZZ ≤ VIL , Cycle Time ≥ tcyc Min	-65	-	330	mA	1,2
			-75	-	320		
Standby Current	ISB	Device deselected, IOUT=0mA, ZZ ≤ VIL, f=Max, All Inputs ≤ VIL or ≥ VIH	-	250	mA		
	ISB1	Device deselected, IOUT=0mA, ZZ ≤ 0.2V, f=0, All Inputs=fixed (VDD-0.2V or 0.2V)	-	200	mA		
	ISB2	Device deselected, IOUT=0mA, ZZ ≥ VDD-0.2V, f=Max, All Inputs ≤ VIL or ≥ VIH	-	200	mA		
Output Low Voltage(3.3V I/O)	VOL	IOL=8.0mA	-	0.4	V		
Output High Voltage(3.3V I/O)	VOH	IOH=-4.0mA	2.4	-	V		
Output Low Voltage(2.5V I/O)	VOL	IOL=1.0mA	-	0.4	V		
Output High Voltage(2.5V I/O)	VOH	IOH=-1.0mA	2.0	-	V		
Input Low Voltage(3.3V I/O)	VIL		-0.3*	0.8	V		
Input High Voltage(3.3V I/O)	VIH		2.0	VDD+0.3**	V	3	
Input Low Voltage(2.5V I/O)	VIL		-0.3*	0.7	V		
Input High Voltage(2.5V I/O)	VIH		1.7	VDD+0.3**	V	3	

Notes : The above parameters are also guaranteed at industrial temperature range.
 1. Reference AC Operating Conditions and Characteristics for input and timing.
 2. Data states are all zero.
 3. In Case of I/O Pins, the Max. VIH=VDDQ+0.3V

Test Conditions

Parameter	Value
Input Pulse Level(for 3.3V I/O)	0 to 3.0V
Input Pulse Level(for 2.5V I/O)	0 to 2.5V
Input Rise and Fall Time(Measured at 20% to 80% for 3.3/2.5V I/O)	1.0V/ns
Input and Output Timing Reference Levels for 3.3V I/O	1.5V
Input and Output Timing Reference Levels for 2.5V I/O	VDDQ/2
Output Load	See Fig. 1

The above parameters are also guaranteed at industrial temperature range.

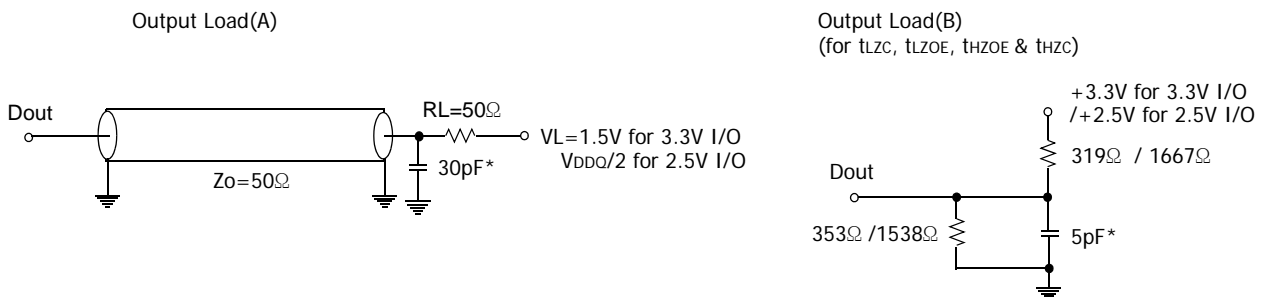


Fig. 1

AC Timing Characteristics

Parameter	Symbol	-65		-75		Unit
		Min	Max	Min	Max	
Cycle Time	t _{CYC}	7.5	-	8.5	-	ns
Clock Access Time	t _{CD}	-	6.5	-	7.5	ns
Output Enable to Data Valid	t _{OE}	-	3.5	-	3.5	ns
Clock High to Output Low-Z	t _{LZC}	2.5	-	2.5	-	ns
Output Hold from Clock High	t _{OH}	2.5	-	2.5	-	ns
Output Enable Low to Output Low-Z	t _{LZOE}	0	-	0	-	ns
Output Enable High to Output High-Z	t _{HZOE}	-	3.5	-	3.5	ns
Clock High to Output High-Z	t _{HZC}	-	3.8	-	4.0	ns
Clock High Pulse Width	t _{CH}	2.5	-	2.5	-	ns
Clock Low Pulse Width	t _{CL}	2.5	-	2.5	-	ns
Address Setup to Clock High	t _{AS}	1.5	-	1.5	-	ns
Address Status Setup to Clock High	t _{SS}	1.5	-	1.5	-	ns
Data Setup to Clock High	t _{DS}	1.5	-	1.5	-	ns
Write Setup to Clock High (\overline{WE} , \overline{BWx})	t _{WS}	1.5	-	1.5	-	ns
Address Advance Setup to Clock High	t _{ADVS}	1.5	-	1.5	-	ns
Chip Select Setup to Clock High	t _{CSS}	1.5	-	1.5	-	ns
Address Hold from Clock High	t _{AH}	0.5	-	0.5	-	ns
Address Status Hold from Clock High	t _{SH}	0.5	-	0.5	-	ns
Data Hold from Clock High	t _{DH}	0.5	-	0.5	-	ns
Write Hold from Clock High (\overline{WE} , \overline{BWx})	t _{WH}	0.5	-	0.5	-	ns
Address Advance Hold from Clock High	t _{ADVH}	0.5	-	0.5	-	ns
Chip Select Hold from Clock High	t _{CSH}	0.5	-	0.5	-	ns
ZZ High to Power Down	t _{PDS}	2	-	2	-	cycle
ZZ Low to Power Up	t _{PUS}	2	-	2	-	cycle

- Notes :**
1. The above parameters are also guaranteed at industrial temperature range.
 2. All address inputs must meet the specified setup and hold times for all rising clock edges whenever \overline{ADSC} and/or \overline{ADSP} is sampled low and \overline{CS} is sampled low. All other synchronous inputs must meet the specified setup and hold times whenever this device is chip selected.
 3. Both chip selects must be active whenever \overline{ADSC} or \overline{ADSP} is sampled low in order for the this device to remain enabled.
 4. \overline{ADSC} or \overline{ADSP} must not be asserted for at least 2 Clock after leaving ZZ state.

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2Mx36 & 4Mx18 Flow-Trough SRAM

Sleep Mode

Sleep Mode is a low current, power-down mode in which the device is deselected and current is reduced to I_{SB2} . The duration of Sleep Mode is dictated by the length of time the ZZ is in a High state.

After entering Sleep Mode, all inputs except ZZ become disabled and all outputs go to High-Z.

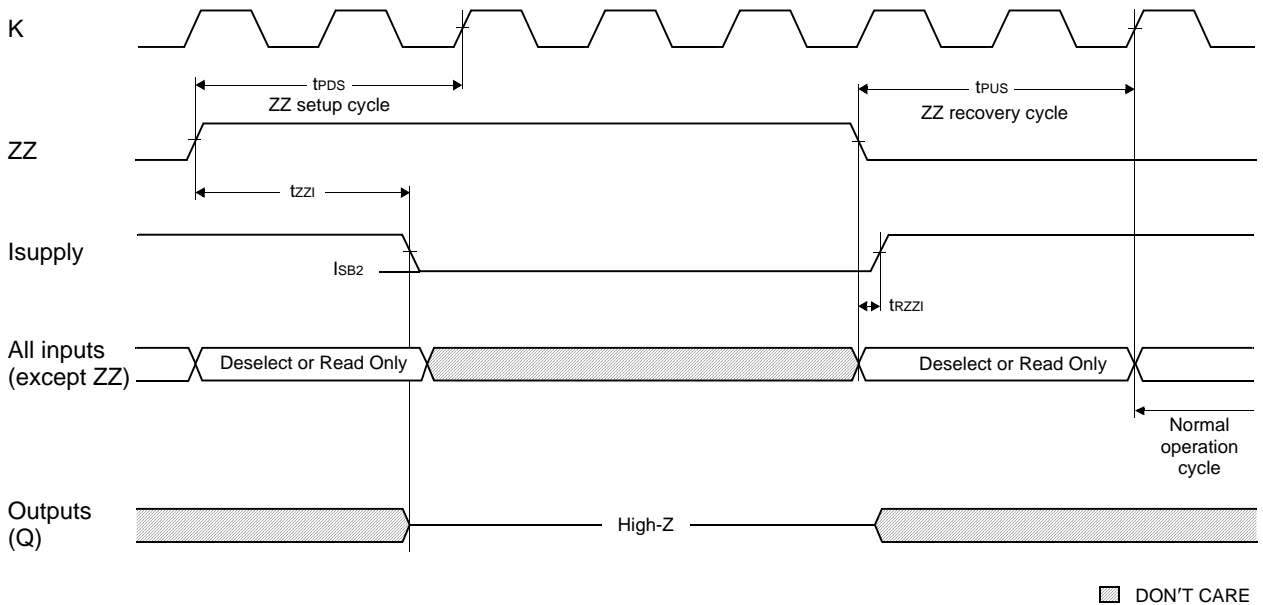
The ZZ pin is an asynchronous, active high input that causes the device to enter Sleep Mode.

When the ZZ pin becomes a logic High, I_{SB2} is guaranteed after the time t_{ZZ1} is met. Any operation pending when entering Sleep Mode is not guaranteed to successful complete. Therefore, Sleep Mode (Read or Write) must not be initiated until valid pending operations are completed. Similarly, when exiting Sleep Mode during t_{PUS} , only a Deselect or Read cycle should be given while the SRAM is transitioning out of Sleep Mode.

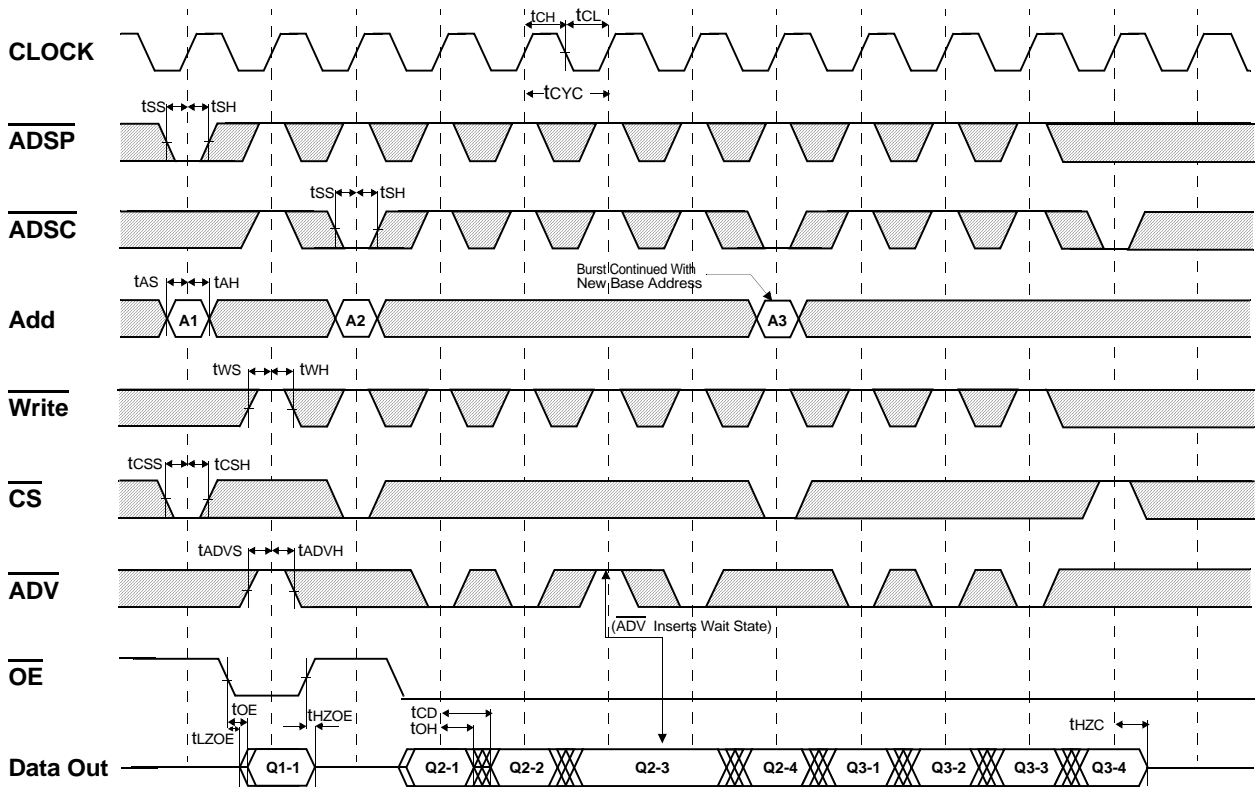
Sleep Mode Electrical Characteristics

Description	Condition	Symbol	Min	Max	Unit
Current during SLEEP MODE	$ZZ \geq V_{IH}$	I_{SB2}		200	mA
ZZ active to input ignored		t_{PDS}	2		cycle
ZZ inactive to input sampled		t_{PUS}	2		cycle
ZZ active to SLEEP current		t_{ZZ1}		2	cycle
ZZ inactive to exit SLEEP current		t_{RZZ1}	0		

Sleep Mode Waveform



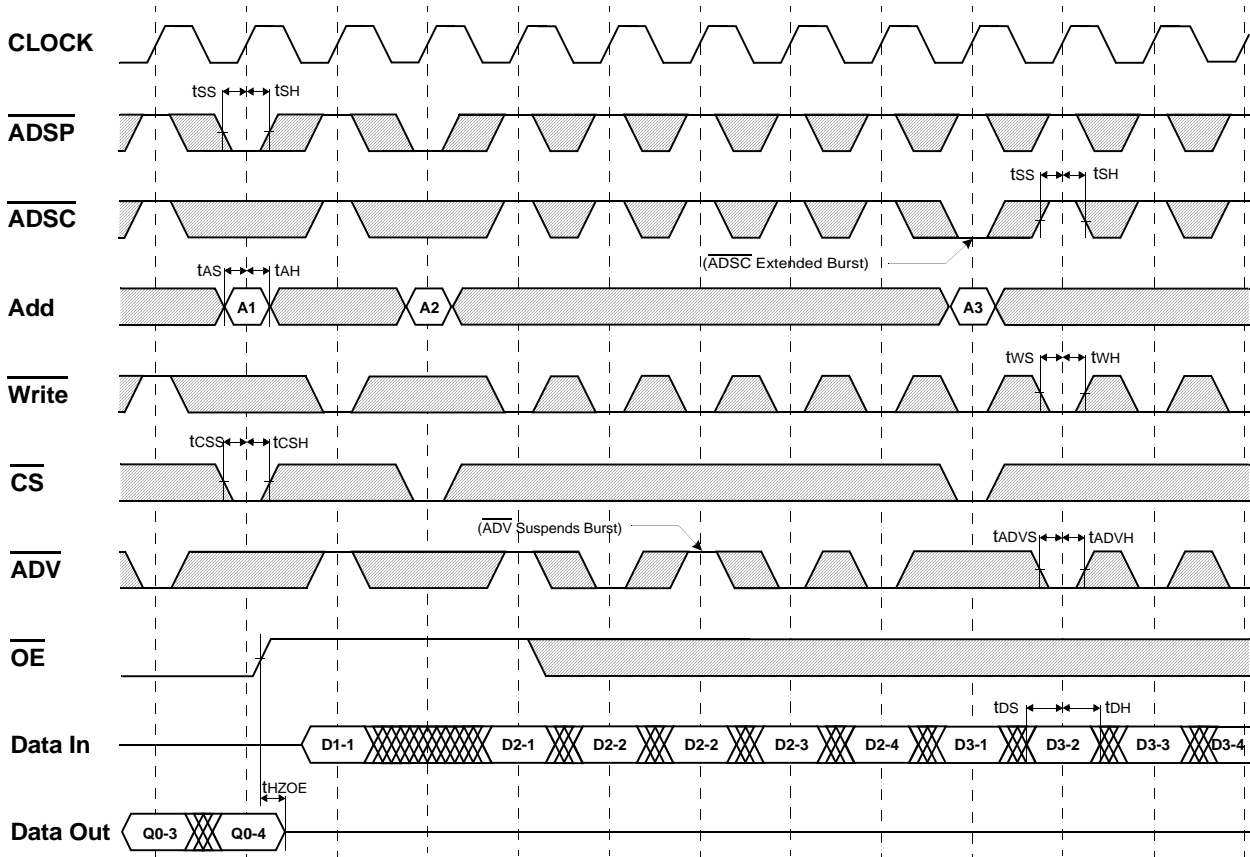
Timing Waveform of Read Cycle



NOTES: $\overline{\text{Write}} = L$ means $\text{GW} = L$, or $\text{GW} = H$, $\text{BW} = L$, $\text{WEx} = L$
 $\overline{\text{CS}} = L$ means $\text{CS}_1 = L$, $\text{CS}_2 = H$ and $\overline{\text{CS}}_2 = L$
 $\overline{\text{CS}} = H$ means $\overline{\text{CS}}_1 = H$, or $\overline{\text{CS}}_1 = L$ and $\overline{\text{CS}}_2 = H$, or $\overline{\text{CS}}_1 = L$, and $\text{CS}_2 = L$

□ Don't Care
 ⊗ Undefined

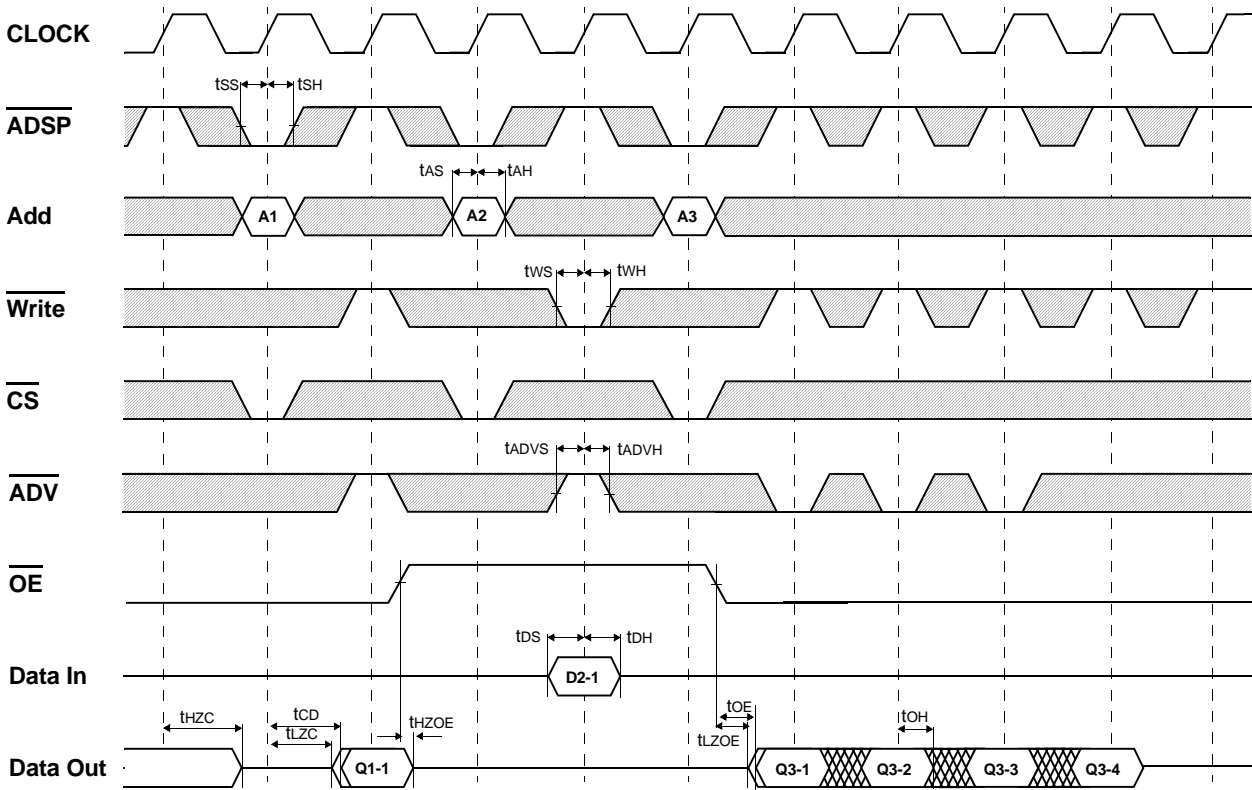
Timing Waveform of Write Cycle



NOTES: $\overline{\text{Write}} = L$ means $\text{GW} = L$, or $\text{GW} = H$, $\text{BW} = L$, $\text{WEX} = L$
 $\overline{\text{CS}} = L$ means $\text{CS}_1 = L$, $\text{CS}_2 = H$ and $\text{CS}_2 = L$
 $\overline{\text{CS}} = H$ means $\text{CS}_1 = H$, or $\text{CS}_1 = L$ and $\text{CS}_2 = H$, or $\text{CS}_1 = L$, and $\text{CS}_2 = L$

□ Don't Care
 ⊠ Undefined

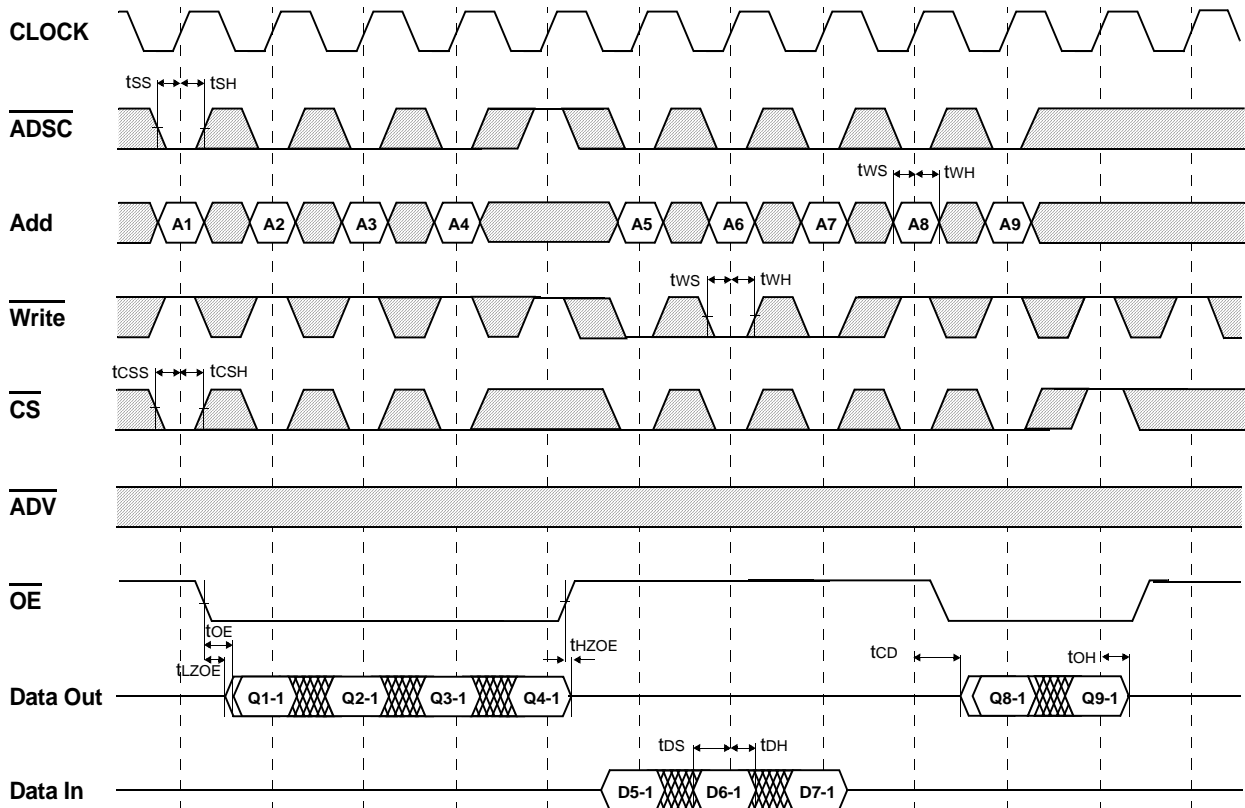
Timing Waveform of Combination Read/Write Cycle(ADSP Controlled , ADSC=High)



NOTES: $\overline{\text{Write}} = \text{L}$ means $\text{GW} = \text{L}$, or $\text{GW} = \text{H}$, $\text{BW} = \text{L}$, $\text{WEX} = \text{L}$
 $\overline{\text{CS}} = \text{L}$ means $\text{CS}_1 = \text{L}$, $\text{CS}_2 = \text{H}$ and $\text{CS}_2 = \text{L}$
 $\overline{\text{CS}} = \text{H}$ means $\text{CS}_1 = \text{H}$, or $\text{CS}_1 = \text{L}$ and $\text{CS}_2 = \text{H}$, or $\text{CS}_1 = \text{L}$, and $\text{CS}_2 = \text{L}$

□ Don't Care
 ▣ Undefined

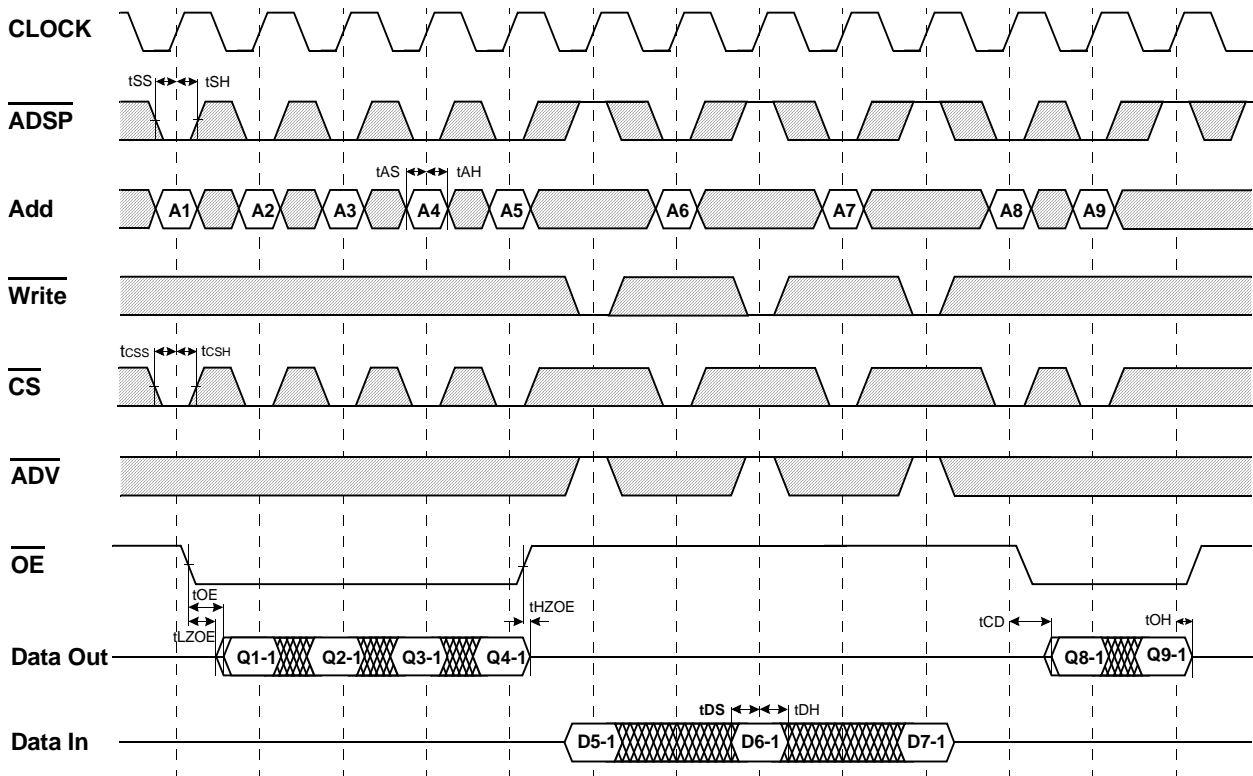
Timing Waveform of Single Read/Write Cycle ($\overline{\text{ADSC}}$ Controlled, $\overline{\text{ADSP}}=\text{High}$)



NOTES: $\overline{\text{Write}} = \text{L}$ means $\text{GW} = \text{L}$, or $\text{GW} = \text{H}$, $\text{BW} = \text{L}$, $\text{WEX} = \text{L}$
 $\overline{\text{CS}} = \text{L}$ means $\overline{\text{CS}}_1 = \text{L}$, $\text{CS}_2 = \text{H}$ and $\overline{\text{CS}}_2 = \text{L}$
 $\overline{\text{CS}} = \text{H}$ means $\overline{\text{CS}}_1 = \text{H}$, or $\overline{\text{CS}}_1 = \text{L}$ and $\overline{\text{CS}}_2 = \text{H}$, or $\overline{\text{CS}}_1 = \text{L}$, and $\text{CS}_2 = \text{L}$

□ Don't Care
 ⊠ Undefined

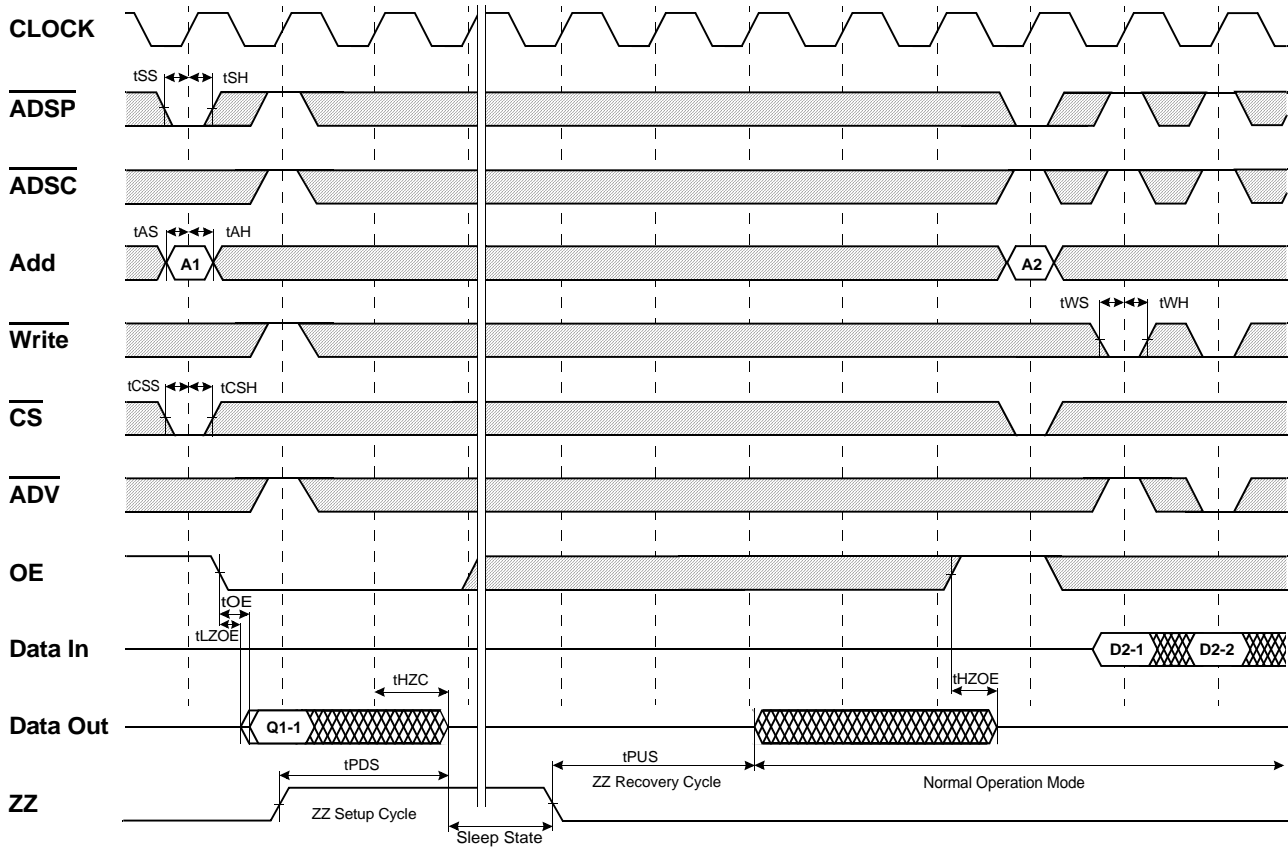
Timing Waveform of Single Read/Write Cycle ($\overline{\text{ADSP}}$ Controlled, $\overline{\text{ADSC}}=\text{High}$)



NOTES: $\overline{\text{Write}} = \text{L}$ means $\text{GW} = \text{L}$, or $\text{GW} = \text{H}$, $\text{BW} = \text{L}$, $\text{WEX} = \text{L}$
 $\overline{\text{CS}} = \text{L}$ means $\overline{\text{CS}}_1 = \text{L}$, $\text{CS}_2 = \text{H}$ and $\overline{\text{CS}}_2 = \text{L}$
 $\overline{\text{CS}} = \text{H}$ means $\overline{\text{CS}}_1 = \text{H}$, or $\overline{\text{CS}}_1 = \text{L}$ and $\overline{\text{CS}}_2 = \text{H}$, or $\overline{\text{CS}}_1 = \text{L}$, and $\text{CS}_2 = \text{L}$

□ Don't Care
 X Undefined

Timing Waveform of Power Down Cycle



NOTES: $\overline{\text{Write}} = \text{L}$ means $\overline{\text{GW}} = \text{L}$, or $\overline{\text{GW}} = \text{H}$, $\overline{\text{BW}} = \text{L}$, $\overline{\text{WEx}} = \text{L}$
 $\overline{\text{CS}} = \text{L}$ means $\overline{\text{CS1}} = \text{L}$, $\overline{\text{CS2}} = \text{H}$ and $\overline{\text{CS2}} = \text{L}$
 $\overline{\text{CS}} = \text{H}$ means $\overline{\text{CS1}} = \text{H}$, or $\overline{\text{CS1}} = \text{L}$ and $\overline{\text{CS2}} = \text{H}$, or $\overline{\text{CS1}} = \text{L}$, and $\overline{\text{CS2}} = \text{L}$

□ Don't Care
 ▨ Undefined

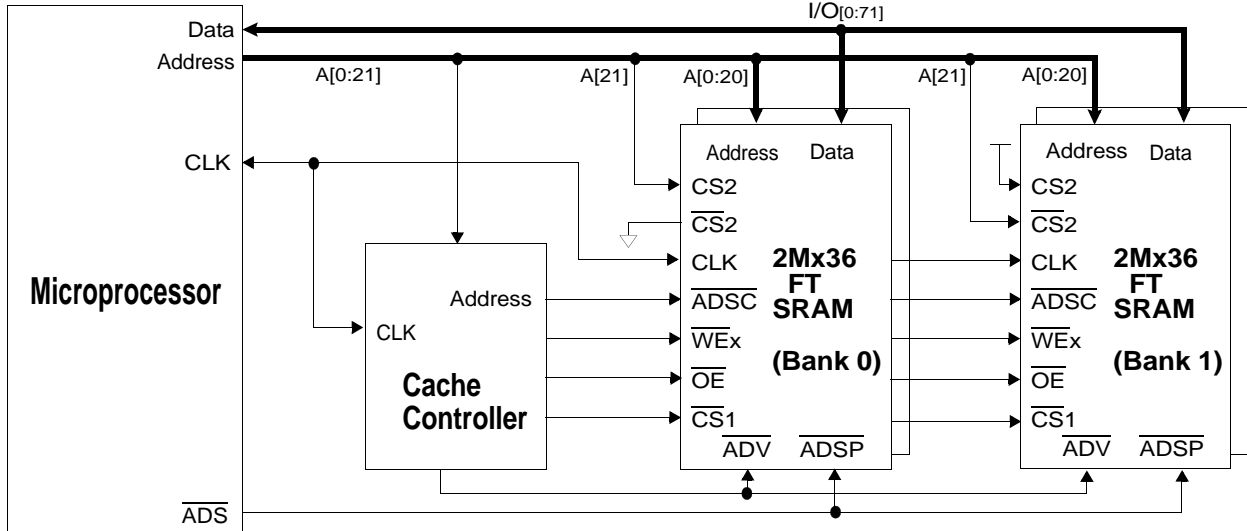
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2Mx36 & 4Mx18 Flow-Trough SRAM

Application Information

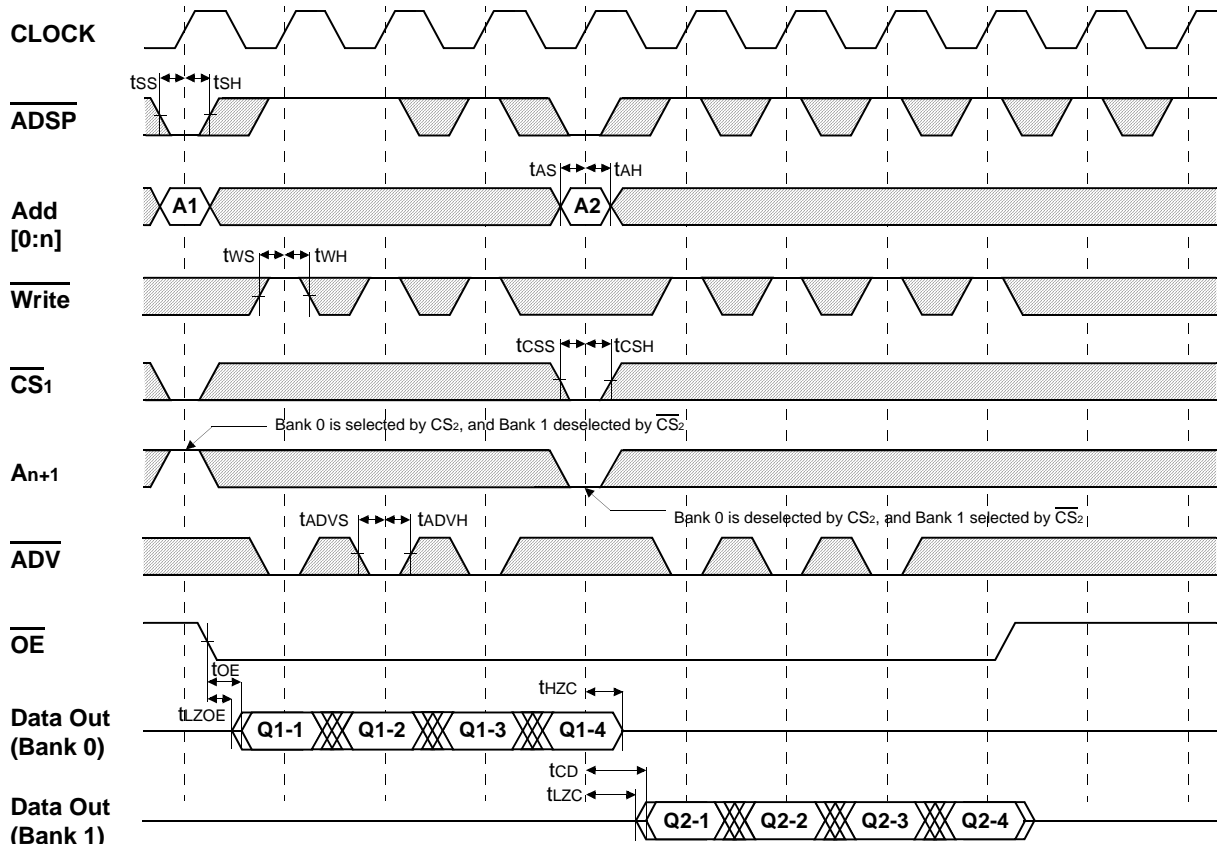
Depth Expansion

The Netsol 2Mx36 Flow-Through SRAM has two additional chip selects for simple depth expansion. This permits easy secondary cache upgrades from 2M depth to 4M depth without extra logic.



Interleave Read Timing (Refer to non-interleave write timing for interleave write timing)

(ADSP Controlled, ADSC=HIGH)



Notes : n = 14 32K depth, 15 64K depth
16 128K depth, 17 256K depth
18 512K depth, 19 1M depth
20 2M depth, 21 4M depth

□ Don't Care ⊗ Undefined

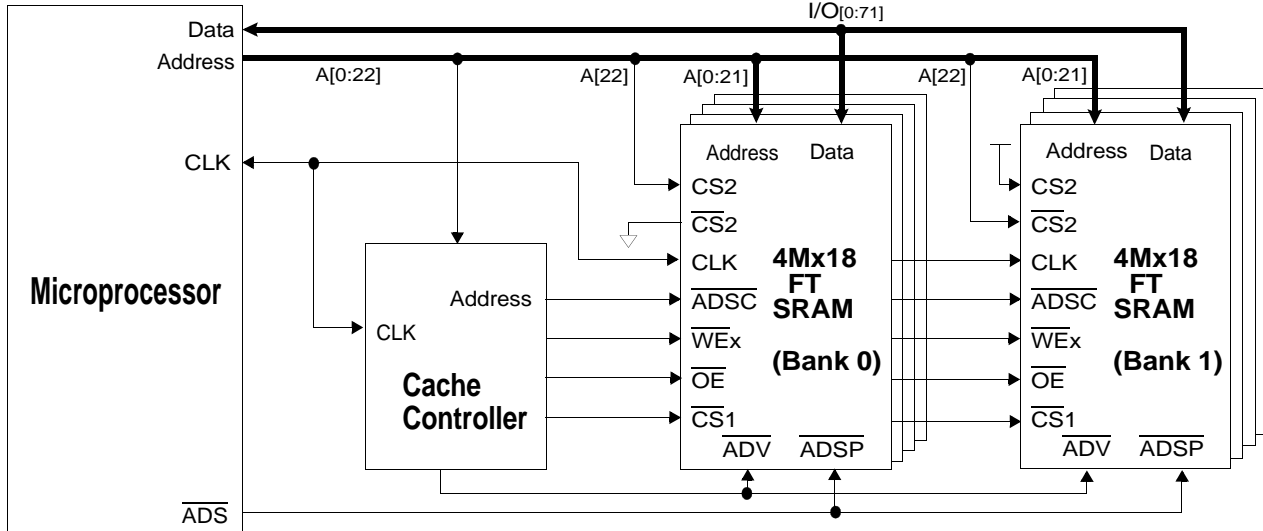
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2Mx36 & 4Mx18 Flow-Trough SRAM

Application Information

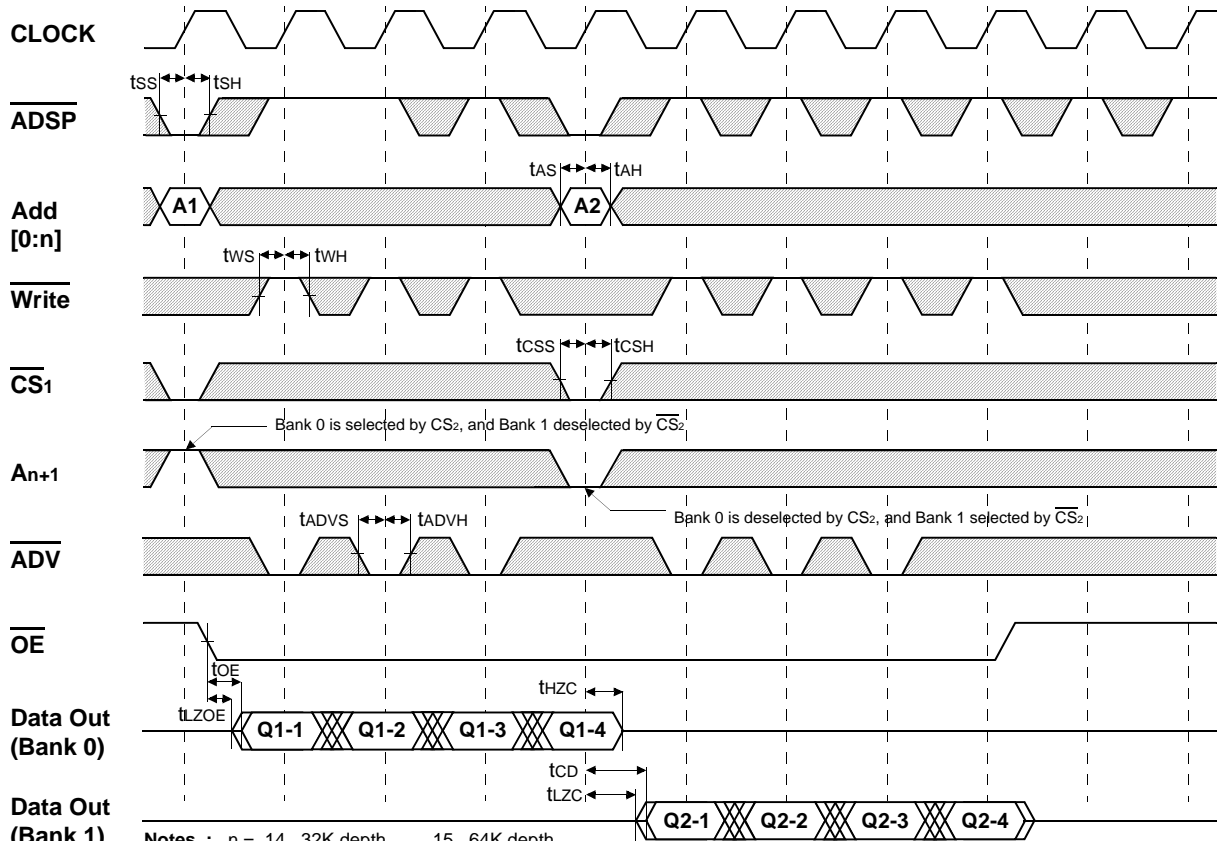
Depth Expansion

The Netsol 4Mx18 Flow-Through SRAM has two additional chip selects for simple depth expansion. This permits easy secondary cache upgrades from 4M depth to 8M depth without extra logic.



Interleave Read Timing (Refer to non-interleave write timing for interleave write timing)

(ADSP Controlled, ADSC=HIGH)



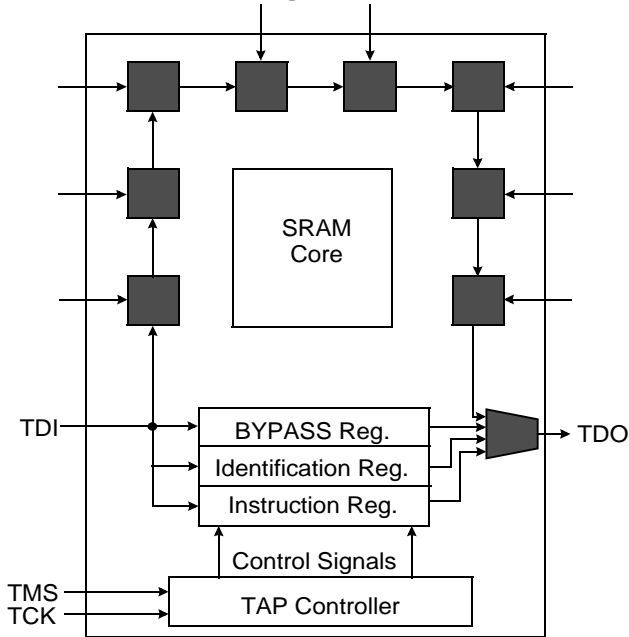
Notes : n = 14 32K depth, 15 64K depth
 16 128K depth, 17 256K depth
 18 512K depth, 19 1M depth
 20 2M depth, 21 4M depth
 22 8M depth

□ Don't Care ⊗ Undefined

IEEE 1149.1 Test Access Port and Boundary Scan-JTAG

This part contains an IEEE standard 1149.1 Compatible Test Access Port (TAP). The package pads are monitored by the Serial Scan circuitry when in test mode. This is to support connectivity testing during manufacturing and system diagnostics. Internal data is not driven out of the SRAM under JTAG control. In conformance with IEEE 1149.1, the SRAM contains a TAP controller, Instruction Register, Bypass Register and ID register. The TAP controller has a standard 16-state machine that resets internally upon power-up, therefore, TRST signal is not required. It is possible to use this device without utilizing the TAP. To disable the TAP controller without interfacing with normal operation of the SRAM, TCK must be tied to Vss to preclude mid level input. TMS and TDI are designed so an undriven input will produce a response identical to the application of a logic 1, and may be left unconnected. But they may also be tied to VDD through a resistor. TDO should be left unconnected.

JTAG Block Diagram



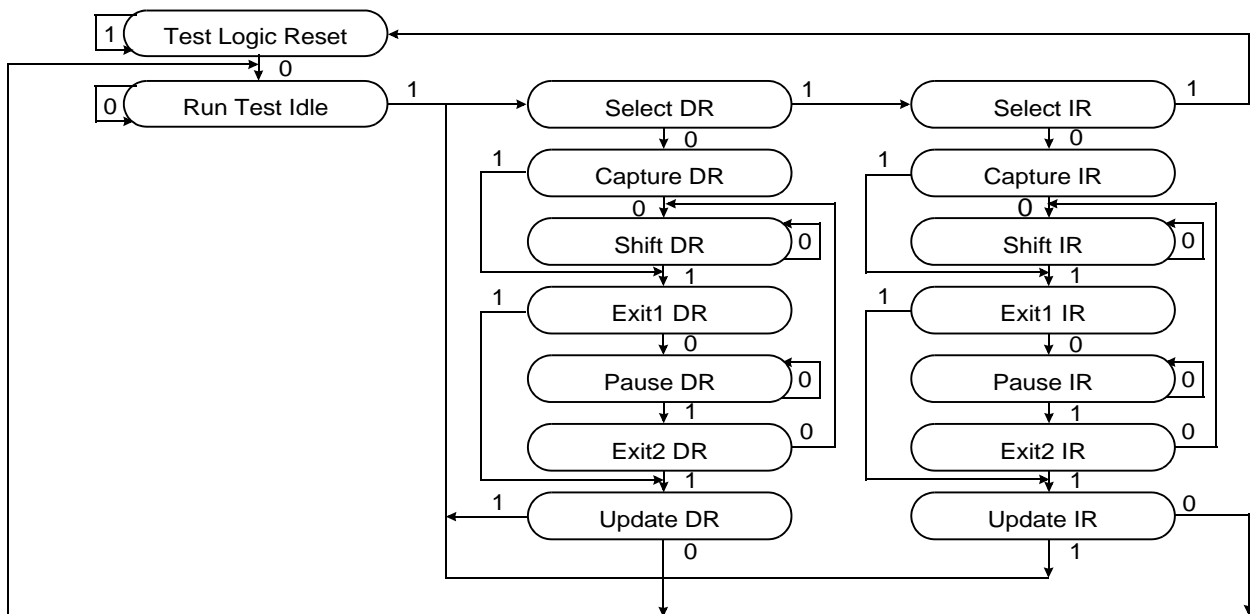
JTAG Instruction Coding

IR2	IR1	IR0	Instruction	TDO Output	Notes
0	0	0	EXTEST	Boundary Scan Register	1
0	0	1	IDCODE	Identification Register	3
0	1	0	SAMPLE-Z	Boundary Scan Register	2
0	1	1	BYPASS	Bypass Register	4
1	0	0	SAMPLE	Boundary Scan Register	5
1	0	1	RESERVED	Do Not Use	6
1	1	0	BYPASS	Bypass Register	4
1	1	1	BYPASS	Bypass Register	4

NOTE:

1. Places DQs in Hi-Z in order to sample all input data regardless of other SRAM inputs. This instruction is not IEEE 1149.1 compliant.
2. Places DQs in Hi-Z in order to sample all input data regardless of other SRAM inputs.
3. TDI is sampled as an input to the first ID register to allow for the serial shift of the external TDI data.
4. Bypass register is initiated to Vss when BYPASS instruction is invoked. The Bypass Register also holds serially loaded TDI when exiting the Shift DR states.
5. SAMPLE instruction dose not places DQs in Hi-Z.
6. This instruction is reserved for future use.

TAP Controller State Diagram



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Scan Register Definition

Part	Instruction Register	Bypass Register	ID Register	Boundary Scan
2M x 36 4M x 18	3 bits	1 bit	32 bits	89 bits

ID Registration Definition

Part	Revision Number (31:28)	Part Configuration (27:18)	Vendor Definition (17:12)	Netsol JEDEC Code (11: 1)	Start Bit(0)
2M x 36	0000	01001 00100	000000	01111011001	1
4M x 18	0000	01010 00011	000000	01111011001	1

Boundary Scan Exit Order

Order	Pin ID
1	6N
2	7N
3	10N
4	11P
5	8P
6	8R
7	9R
8	9P
9	10P
10	10R
11	11R
12	11H
13	11N
14	11M
15	11L
16	11K
17	11J
18	10M
19	10L
20	10K
21	10J
22	9H
23	10H
24	11G
25	11F
26	11E
27	11D
28	10G
29	10F
30	10E
31	10D
32	11C
33	11A
34	11B
35	10A
36	10B

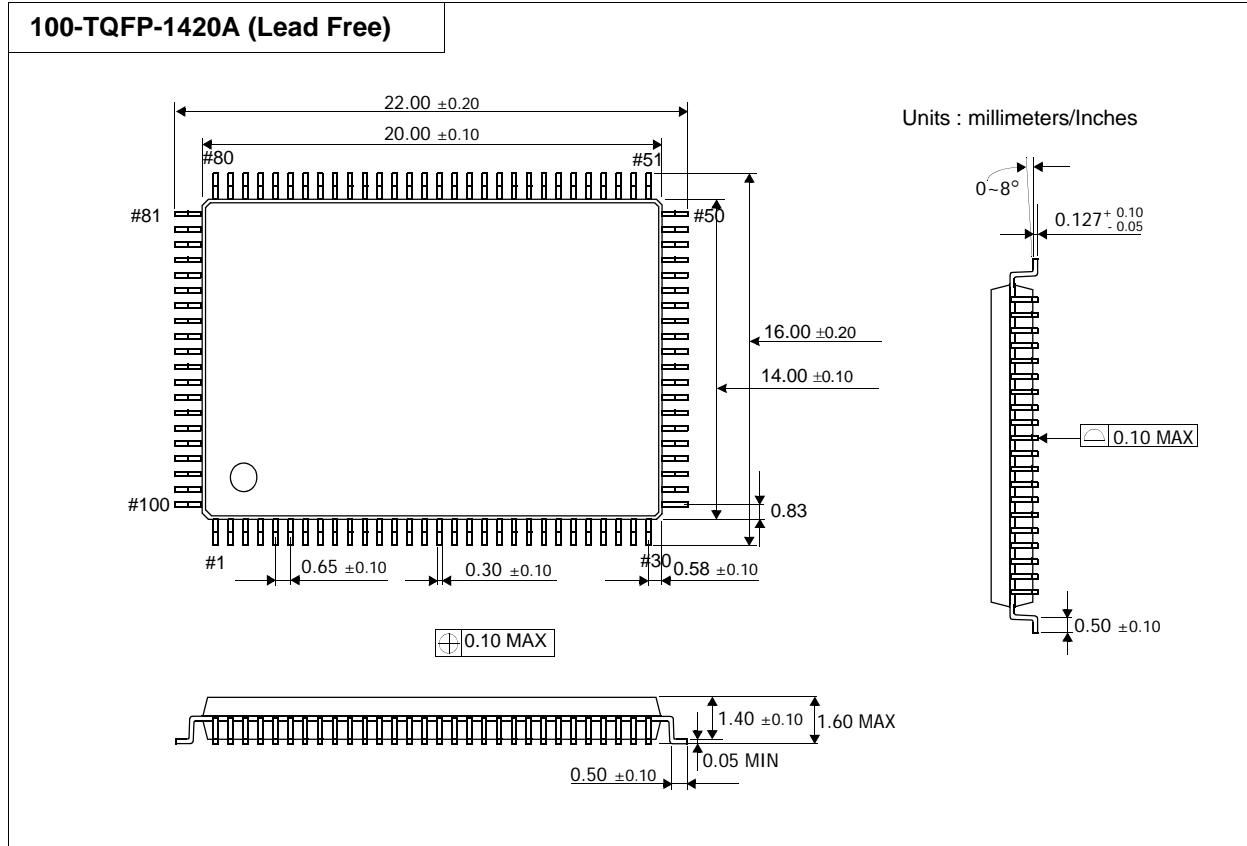
Order	Pin ID
37	9A
38	9B
39	10C
40	8A
41	8B
42	7A
43	7B
44	6B
45	6A
46	5B
47	5A
48	4A
49	4B
50	3B
51	3A
52	2A
53	2B
54	2C
55	1B
56	1A
57	1C
58	1D
59	1E
60	1F
61	1G
62	2D
63	2E
64	2F
65	2G
66	1H
67	3H
68	1J
69	1K
70	1L
71	1M
72	2J

Order	Pin ID
73	2K
74	2L
75	2M
76	1N
77	2N
78	1P
79	1R
80	2R
81	3P
82	3R
83	2P
84	4R
85	4P
86	5N
87	6P
88	6R
89	Internal

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2Mx36 & 4Mx18 Flow-Trough SRAM

Package Dimensions

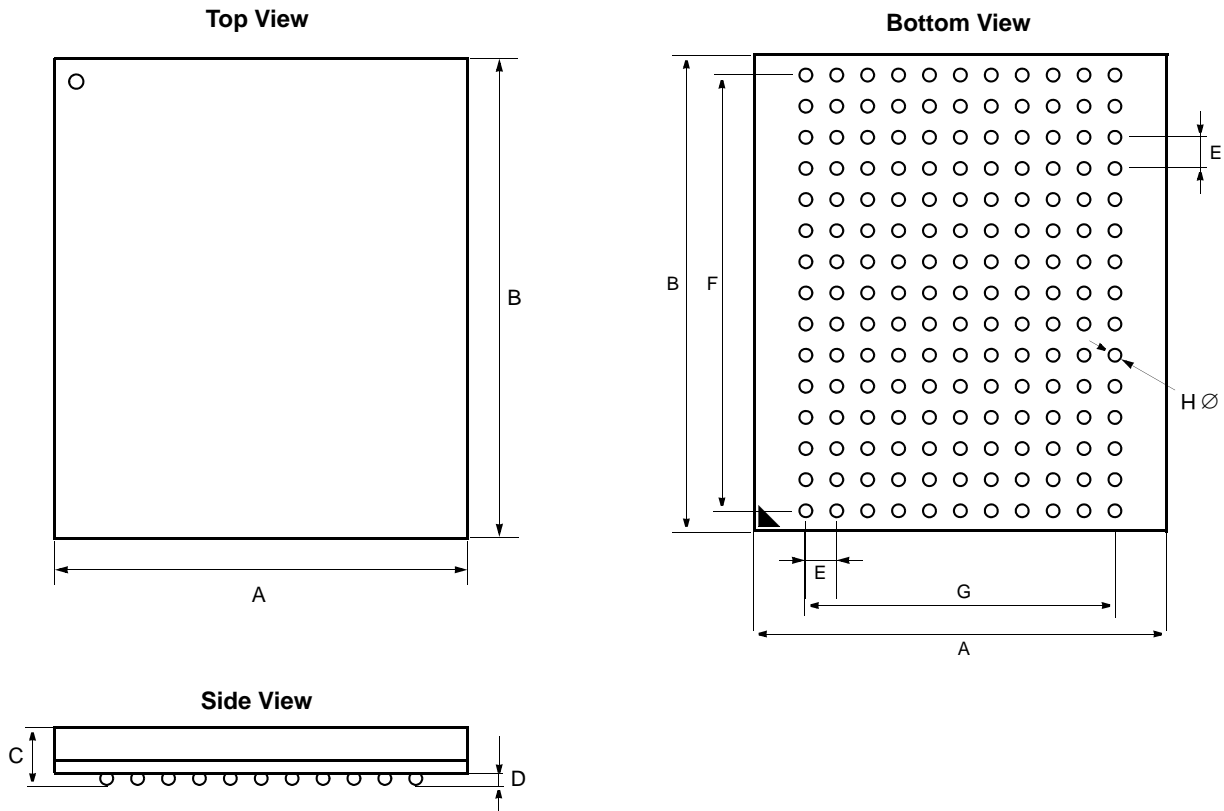


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2Mx36 & 4Mx18 Flow-Trough SRAM

165 FBGA Package Dimensions (Lead Free)

13mm x 15mm Body, 1.0mm Bump Pitch, 11x15 Ball Grid Array



Symbol	Value	Units	Note	Symbol	Value	Units	Note
A	13 ± 0.1	mm		E	1.0	mm	
B	15 ± 0.1	mm		F	14.0	mm	
C	1.3 ± 0.1	mm		G	10.0	mm	
D	0.35 ± 0.05	mm		H	0.5 ± 0.05	mm	